

## PATENT ASSIGNMENT COVER SHEET

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Assignment ID: PATI48682

<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
Hyung-suk CHOI	04/18/2012
Hyun-tae JUNG	04/18/2012
Eung-ryul PARK	04/18/2012
Da-soon LEE	04/18/2012
<b>RECEIVING PARTY DATA</b>	
<b>Company Name:</b>	Magnachip Semiconductor, Ltd.
<b>Street Address:</b>	1, Hyangjeong-dong, Hungduk-gu, Chungbuk
<b>City:</b>	Cheongju-si
<b>State/Country:</b>	KOREA, REPUBLIC OF
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
Application Number:	14788090
<b>CORRESPONDENCE DATA</b>	
<b>Fax Number:</b>	2023153758
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<b>ATTORNEY DOCKET NUMBER:</b>	030103.0019D1
<b>NAME OF SUBMITTER:</b>	Isabelle Osborne
<b>SIGNATURE:</b>	Isabelle Osborne
<b>DATE SIGNED:</b>	02/23/2024
<b>Total Attachments: 2</b>	
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**ASSIGNMENT**

For valuable consideration, we,

<b>Hyung-suk CHOI</b>	214-1106, Hyundai 2-cha, Bokdae-dong, Heungdeok-gu, Cheongju-si, Chungcheongbuk-do, Republic of Korea
<b>Hyun-tae JUNG</b>	304, Goldengrivil, 2548-1, Bongmyeong-dong, Heungdeok-gu, Cheongju-si, Chungcheongbuk-do, Republic of Korea
<b>Eung-ryul PARK</b>	202-303, Kumho Eoullim Apt., Bokdae-dong, Heungdeok-gu, Cheongju-si, Chungcheongbuk-do, Republic of Korea
<b>Da-soon LEE</b>	112-1402, Kumho Eoullim Apt., Bokdae-dong, Heungdeok-gu, Cheongju-si, Chungcheongbuk-do, Republic of Korea

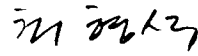
hereby assign to:

**MAGNACHIP SEMICONDUCTOR, LTD.**, a Republic of Korea  
corporation/institution/foundation/institute having principal executive office(s) or place  
of business at: 1, Hyangjeong-dong, Hungduk-gu, Cheongju-si, Chungbuk, Republic of  
Korea; and

its successors and assigns (collectively hereinafter called "the Assignee"), the entire right, title and interest throughout the world in the inventions and improvements which are subject of U.S. Patent Application Number 13/465593 filed May 7, 2012 at the U.S. Patent & Trademark Office signed by us, with title **ISOLATION STRUCTURE, SEMICONDUCTOR DEVICE HAVING THE SAME, AND METHOD FOR FABRICATING THE ISOLATION STRUCTURE**, and we authorize and request the attorneys appointed in said application to hereafter complete this assignment by inserting above the filing date and application serial number of said application when known; this Assignment including said application, any and all United States and foreign patents, utility models, and design registrations granted for any of said inventions or improvements, and the right to claim priority based on the filing date of said application under the International Convention for the Protection of Industrial Property, the Patent Cooperation Treaty, the European Patent Convention, and all other treaties of like purposes; and we authorize the Assignee to apply in all countries in our name or in its own name for patents, utility models, design registrations and like rights of exclusion and for inventors' certificates for said inventions and improvements; and we agree for ourselves and our respective heirs, legal representatives and assigns, without further compensation to perform such lawful acts and to sign such further applications, assignments, preliminary statements and other lawful documents as the Assignee may reasonably request to effectuate fully this Assignment.


IN TESTIMONY/WITNESS WHEREOF, we, undersigned inventors (Assignors) intending to be legally bound, have hereto affixed our signatures.

This 18 day of April, 2012



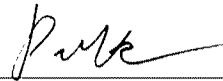
Signature: Hyung-suk CHOI

This 18 day of April, 2012



Signature: Hyun-tae JUNG

This 18 day of April, 2012



Signature: Fung-ryul PARK

This 18 day of April, 2012



Signature: Da-soon LEE